

ABSTRACT OF THE DISCLOSURE

A substrate processing device includes a top ring, a swing cover fixed to the top ring, a turntable to which a polishing pad is attachable and that rotates the polishing pad, and an atomizer that supplies a washing fluid to the polishing pad, in which when a top ring head is at a transfer position for transferring a substrate, the swing cover is positioned between the substrate and the polishing pad, and when the top ring head is at a polishing position for polishing the substrate with the polishing pad, the swing cover does not overlap the polishing pad in a plan view.

Fig. 2